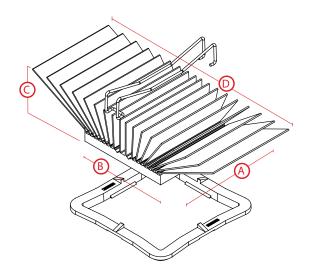


Ultra High Performance BGA Cooling Solutions w/ maxiGRIP™ Attachment

ATS PART # ATS-51230K-C2-R0

Features & Benefits

- » maxiFLOW™ design features a low profile, spread fin array that maximizes surface area for more effective convection (air) cooling
- » maxiGRIP™ attachment applies steady, even pressure to the component and does not require holes in the PCB
- » Meets Telcordia GR-63-Core Office Vibration; ETSI 300 019 Transportation Vibration; and MIL-STD-810 Shock and Unpackaged Drop Testing standards
- » Comes preassembled with high performance, phase changing, thermal interface material
- » Designed for low profile components from 1.5 to 2.99mm





Thermal Performance

*Image above is for illustration purposes only.

AIR VELOCITY		THERMAL RESISTANCE		
FT/MIN	M/S	°C/W (UNDUCTED FLOW)	°C/W (DUCTED FLOW)	
200	1.0	6.6	5.1	
300	1.5	5.4		
400	2.0	4.7		
500	2.5	4.2		
600	3.0	3.9		
700	3.5	3.6		
800	4.0	3.4		

Product Details

DIMENSION A	DIMENSION B	DIMENSION C	DIMENSION D	INTERFACE MATERIAL	FINISH
23 mm	23 mm	14.5 mm	41.5 mm	SAINT-GOBAIN C1100F	BLACK- ANODIZED

NOTES:

- Dimension C = heat sink height from bottom of the base to the top of the fin field.
- ATS-51230K-C1-R0 is a subsitute item available utilizing an equivalent phase change material (Chomerics T766).
- Thermal performance data are provided for reference only. Actual performance may vary by application.
- ATS reserves the right to update or change its products without notice to improve the design or performance.
- optional maxiGRIP™ Installation/Removal Tool Set P/N: MGT230
- 6) Contact ATS to learn about custom options available.



For more information, to find a distributor or to place an order, visit www.qats.com or call: 781.769.2800 (North America); +31 (0) 3569 84715 (Europe).